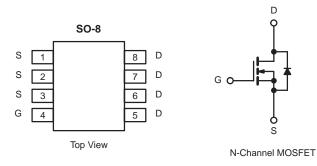


IRF7401TRPBF-VB Datasheet

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)		
30	0.016 at V _{GS} = 10 V	6.8	9.2 nC		
30	0.029 at V_{GS} = 4.5 V	5.8	9.2 110		



FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Notebook Load Switch
- Low Current dc-to-dc



Available

ABSOLUTE MAXIMUM RATINGS $T_A = 25 \text{ °C}$, unless otherwise noted							
Parameter	Symbol	Limit	Unit				
Drain-Source Voltage	V _{DS}	30	V				
Gate-Source Voltage	V _{GS}	± 20	v				
	T _C = 25 °C		6.8 ^a				
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		5 ^a				
Continuous Drain Current (1) = 150°C)	T _A = 25 °C	l I _D	6.5 ^{b,c}				
	T _A = 70 °C	1	4.9 ^{b,c}	А			
Pulsed Drain Current	I _{DM}	30					
Continuous Source-Drain Diode Current	T _C = 25 °C		2.7				
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	1.7 ^{b,c}				
	T _C = 25 °C		4.1				
Movimum Dowor Dissinction	T _C = 70 °C		2.6	w			
Maximum Power Dissipation	T _A = 25 °C	P _D	2 ^{b,c}	vv			
	T _A = 70 °C	1 [1.25 ^{b,c}				
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C				

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	$t \le 5 s$	R _{thJA}	45	62.5	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	25	30	C/W	

Notes:

a. Package Limited.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under Steady State conditions is 110 $^{\circ}\text{C/W}.$



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			33		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 6.2		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1		3	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zara Cata Valtaga Drain Current	1	V _{DS} = 30 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			10	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α
	D	V _{GS} = 10 V, I _D = 5 A	0.016			Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_{D} = 4 \text{ A}$		0.029		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 5 A		24		S
Dynamic ^b						
Input Capacitance	C _{iss}			1295		
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		170		pF
Reverse Transfer Capacitance	C _{rss}			72		
Total Gate Charge	Q _g	$V_{DS} = 15 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}$		21.8	33	
				9.2	14	nC
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		3.8		
Gate-Drain Charge	Q _{gd}			2.5		
Gate Resistance	R _g	f = 1 MHz		2.4		Ω
Turn-On Delay Time	t _{d(on)}			21	40	
Rise Time	t _r	V_{DD} = 15 V, R_L = 3 Ω		14	25	1
Turn-Off DelayTime	t _{d(off)}	$\text{I}_\text{D} \cong$ 5 A, V_GEN = 4.5 V, R_g = 1 Ω		20	40	
Fall Time	t _f			9	18	
Turn-On Delay Time	t _{d(on)}			10	20	ns
Rise Time	t _r	V_{DD} = 15 V, R_L = 3 Ω		8	16	-
Turn-Off DelayTime	t _{d(off)}	${ m I}_{ m D}{\cong}5$ A, ${ m V}_{ m GEN}$ = 10 V, ${ m R}_{ m g}$ = 1 Ω		21	35	
Fall Time	t _f			8	16	
Drain-Source Body Diode Characterist	ics					•
Continous Source-Drain Diode Current	۱ _S	T _C = 25 °C			2.7	^
Pulse Diode Forward Current	I _{SM}				30	A
Body Diode Voltage	V _{SD}	I _S = 1.7 A, V _{GS} = 0 V		0.77	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			21	40	ns
Body Diode Reverse Recovery Charge	Q _{rr}	L = 3 A dl/dt = 100 A/up T = 25 °C		15	30	nC
Reverse Recovery Fall Time	t _a	$I_F = 3 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		13		
Reverse Recovery Rise Time	t _b			8		ns

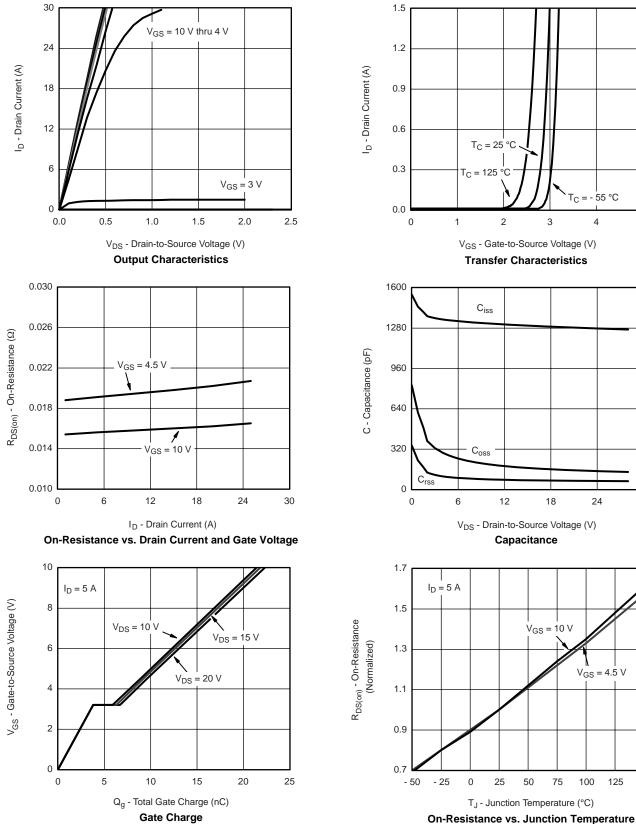
Notes:

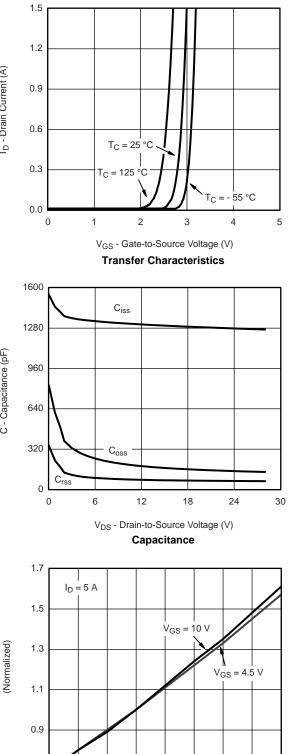
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



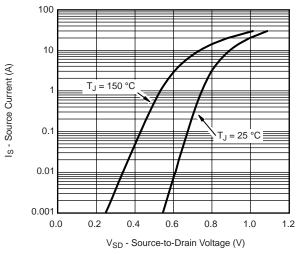


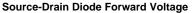


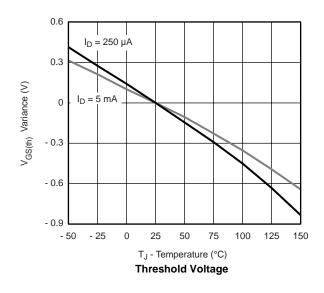
T_J - Junction Temperature (°C)

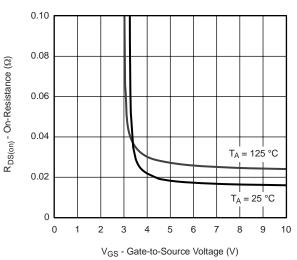
服务热线:400-655-8788



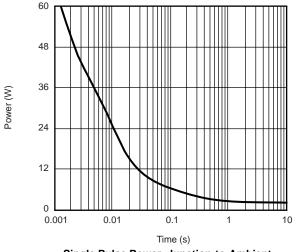




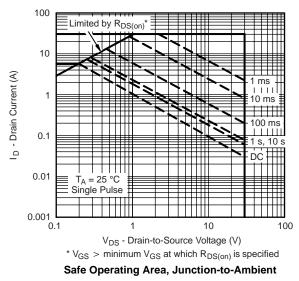




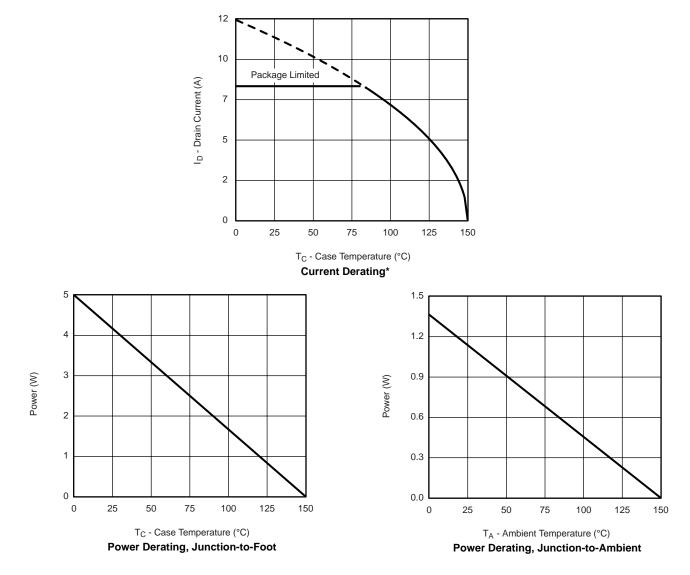
On-Resistance vs. Gate-to-Source Temperature



Single Pulse Power, Junction-to-Ambient

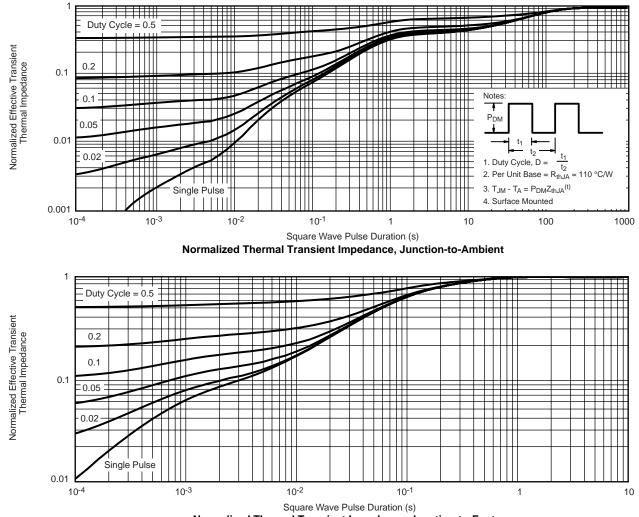






* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



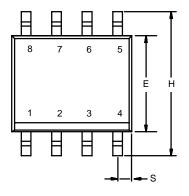


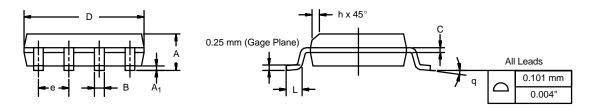
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

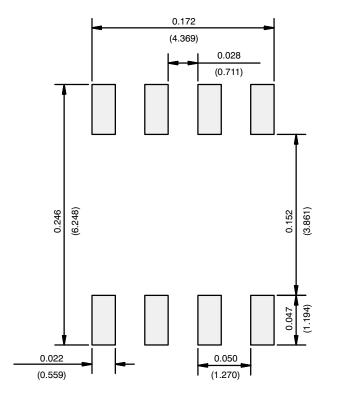




	MILLIMETERS		INC	HES		
DIM	Min	Мах	Min	Max		
A	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	1.27 BSC		BSC		
н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498						



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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